ON Semiconductor

PRODUCT BULLETIN #20710

Generic Copy

Issue Date: 19-Dec-2014

TITLE: Change to pocket tray.

PROPOSED FIRST SHIP DATE: 30-Jan-2015

AFFECTED CHANGE CATEGORY(S): Packing

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or <Gretel.Willems@onsemi.com>

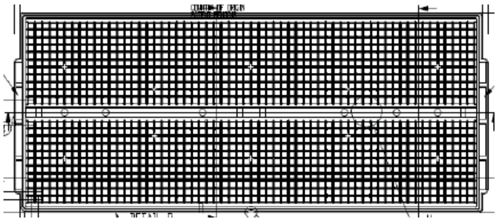
NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific concerns are provided in writing. To do so, contact quality@onsemi.com within 14 days after date issued.

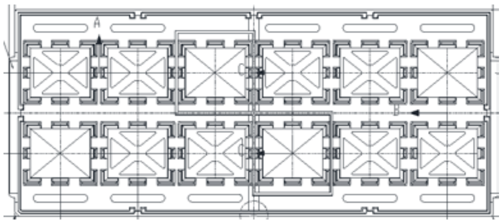
DESCRIPTION of CHANGEPURPOSE:

In order to decrease the risk for pin bending on our products we have improved the design of our trays. This is realized by means of individual pockets designed specifically for these devices.
Both Minimum Packing Quantity (MPQ) and Minimum Order Quantity (MOQ) are not affected by this change.

Old tray:



New tray:



The outer dimensions remain identical.

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PURPOSE of CHANGE:

This change is a quality improvement by reducing the risk of pin bending by packing/unpacking the devices.

List of affected General Parts:

NOIV1SE025KA-GDC
NOIV1SN025KA-GDC

List of affected Customer Specific Parts:

NOICPSNEAGLA-GBC